Intel - EP4CE75F29C9LN Datasheet





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Details

Product Status	Active
Number of LABs/CLBs	4713
Number of Logic Elements/Cells	75408
Total RAM Bits	2810880
Number of I/O	426
Number of Gates	-
Voltage - Supply	0.97V ~ 1.03V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	780-BGA
Supplier Device Package	780-FBGA (29x29)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce75f29c9ln

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Cyclone IV Device Family Architecture

This section describes Cyclone IV device architecture and contains the following topics:

- "FPGA Core Fabric"
- "I/O Features"
- "Clock Management"
- "External Memory Interfaces"
- "Configuration"
- "High-Speed Transceivers (Cyclone IV GX Devices Only)"
- "Hard IP for PCI Express (Cyclone IV GX Devices Only)"

FPGA Core Fabric

Cyclone IV devices leverage the same core fabric as the very successful Cyclone series devices. The fabric consists of LEs, made of 4-input look up tables (LUTs), memory blocks, and multipliers.

Each Cyclone IV device M9K memory block provides 9 Kbits of embedded SRAM memory. You can configure the M9K blocks as single port, simple dual port, or true dual port RAM, as well as FIFO buffers or ROM. They can also be configured to implement any of the data widths in Table 1–7.

Table 1–7. M9K Block Data Widths for Cyclone IV Device Family

Mode	Data Width Configurations		
Single port or simple dual port	×1, ×2, ×4, ×8/9, ×16/18, and ×32/36		
True dual port	×1, ×2, ×4, ×8/9, and ×16/18		

The multiplier architecture in Cyclone IV devices is the same as in the existing Cyclone series devices. The embedded multiplier blocks can implement an 18 × 18 or two 9 × 9 multipliers in a single block. Altera offers a complete suite of DSP IP including finite impulse response (FIR), fast Fourier transform (FFT), and numerically controlled oscillator (NCO) functions for use with the multiplier blocks. The Quartus[®] II design software's DSP Builder tool integrates MathWorks Simulink and MATLAB design environments for a streamlined DSP design flow.



For more information, refer to the *Logic Elements and Logic Array Blocks in Cyclone IV Devices*, *Memory Blocks in Cyclone IV Devices*, and *Embedded Multipliers in Cyclone IV Devices* chapters.

Arithmetic Mode

Arithmetic mode is ideal for implementing adders, counters, accumulators, and comparators. An LE in arithmetic mode implements a 2-bit full adder and basic carry chain (Figure 2–3). LEs in arithmetic mode can drive out registered and unregistered versions of the LUT output. Register feedback and register packing are supported when LEs are used in arithmetic mode.

Figure 2–3 shows LEs in arithmetic mode.





The Quartus II Compiler automatically creates carry chain logic during design processing. You can also manually create the carry chain logic during design entry. Parameterized functions, such as LPM functions, automatically take advantage of carry chains for the appropriate functions.

The Quartus II Compiler creates carry chains longer than 16 LEs by automatically linking LABs in the same column. For enhanced fitting, a long carry chain runs vertically, which allows fast horizontal connections to M9K memory blocks or embedded multipliers through direct link interconnects. For example, if a design has a long carry chain in an LAB column next to a column of M9K memory blocks, any LE output can feed an adjacent M9K memory block through the direct link interconnect. If the carry chains run horizontally, any LAB which is not next to the column of M9K memory blocks uses other row or column interconnects to drive a M9K memory block. A carry chain continues as far as a full column. Figure 4–2 shows the multiplier block architecture.



Figure 4–2. Multiplier Block Architecture

Input Registers

You can send each multiplier input signal into an input register or directly into the multiplier in 9- or 18-bit sections, depending on the operational mode of the multiplier. You can send each multiplier input signal through a register independently of other input signals. For example, you can send the multiplier Data A signal through a register and send the Data B signal directly to the multiplier.

The following control signals are available for each input register in the embedded multiplier:

- clock
- clock enable
- asynchronous clear

All input and output registers in a single embedded multiplier are fed by the same clock, clock enable, and asynchronous clear signals.

Multiplier Stage

The multiplier stage of an embedded multiplier block supports 9×9 or 18×18 multipliers, as well as other multipliers between these configurations. Depending on the data width or operational mode of the multiplier, a single embedded multiplier can perform one or two multiplications in parallel. For multiplier information, refer to "Operational Modes" on page 4–4.

Each multiplier operand is a unique signed or unsigned number. The signa and signb signals control an input of a multiplier and determine if the value is signed or unsigned. If the signa signal is high, the Data A operand is a signed number. If the signa signal is low, the Data A operand is an unsigned number.

Signal Name	Description	Source	Destination
scanclk	Free running clock from core used in combination with phasestep to enable or disable dynamic phase shifting. Shared with scanclk for dynamic reconfiguration.	GCLK or I/O pins	PLL reconfiguration circuit
phasedone	When asserted, it indicates to core logic that the phase adjustment is complete and PLL is ready to act on a possible second adjustment pulse. Asserts based on internal PLL timing. De-asserts on the rising edge of scanclk.	PLL reconfiguration circuit	Logic array or I/O pins

Table 5-12.	Dvnamic	Phase	Shiftina	Control	Signals	(Part 2 of 2	1
						1	

Table 5–13 lists the PLL counter selection based on the corresponding PHASECOUNTERSELECT setting.

Table 5–13. Phase Counter Select Mapping

	phasecounterselec	t	Salaata
[2]	[1]	[0]	Selects
0	0	0	All Output Counters
0	0	1	M Counter
0	1	0	C0 Counter
0	1	1	C1 Counter
1	0	0	C2 Counter
1	0	1	C3 Counter
1	1	0	C4 Counter

To perform one dynamic phase-shift, follow these steps:

- 1. Set PHASEUPDOWN and PHASECOUNTERSELECT as required.
- 2. Assert PHASESTEP for at least two SCANCLK cycles. Each PHASESTEP pulse allows one phase shift.
- 3. Deassert PHASESTEP after PHASEDONE goes low.
- 4. Wait for PHASEDONE to go high.
- 5. Repeat steps 1 through 4 as many times as required to perform multiple phaseshifts.

<code>PHASEUPDOWN</code> and <code>PHASECOUNTERSELECT</code> signals are synchronous to <code>SCANCLK</code> and must meet the t_{su} and t_h requirements with respect to the <code>SCANCLK</code> edges.

You can repeat dynamic phase-shifting indefinitely. For example, in a design where the VCO frequency is set to 1,000 MHz and the output clock frequency is set to 100 MHz, performing 40 dynamic phase shifts (each one yields 125 ps phase shift) results in shifting the output clock by 180°, in other words, a phase shift of 5 ns.

Section II. I/O Interfaces

This section provides information about Cyclone[®] IV device family I/O features and high-speed differential and external memory interfaces.

This section includes the following chapters:

- Chapter 6, I/O Features in Cyclone IV Devices
- Chapter 7, External Memory Interfaces in Cyclone IV Devices

Revision History

Refer to each chapter for its own specific revision history. For information about when each chapter was updated, refer to the Chapter Revision Dates section, which appears in the complete handbook.

The CLKIN/REFCLK pins are powered by dedicated V_{CC_CLKIN3A}, V_{CC_CLKIN3B}, V_{CC_CLKIN3B}, v_{CC_CLKIN8A}, and V_{CC_CLKIN8B} power supplies separately in their respective I/O banks to avoid the different power level requirements in the same bank for GPIO.

				VCC_CLKIN Level		I/O Pin Type			
I/O Standard HSSI Protocol C		Coupling	Termination	Input	Output	Column I/O	Row I/O	Supported I/O Banks	
LVDS	All		Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B	
LVPECL	All	Differential AC (Need	Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B	
	All	off chip resistor to	Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B	
1.2V, 1.5V, 3.3V PCML	All	restore V _{CM})	Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B	
	All		Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B	
HCSL	PCIe	Differential DC	Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B	

Table 6–10. Cyclone IV GX HSSI REFCLK I/O Standard Support Using GPIO CLKIN Pins (1), (2)

Notes to Table 6-10:

(1) The EP4CGX15, EP4CGX22, and EP4CGX30 devices have two pairs of dedicated clock input pins in banks 3A and 8A for HSSI input reference clock. I/O banks 3B and 8B are not available in EP4CGX15, EP4CGX22, and EP4CGX30 devices.

(2) The EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices have four pairs of dedicated clock input pins in banks 3A, 3B, 8A, and 8B for HSSI input or single-ended clock input.

To For more information about the AC-coupled termination scheme for the HSSI reference clock, refer to the *Cyclone IV Transceivers Architecture* chapter.

LVDS I/O Standard Support in Cyclone IV Devices

The LVDS I/O standard is a high-speed, low-voltage swing, low power, and GPIO interface standard. Cyclone IV devices meet the ANSI/TIA/EIA-644 standard with the following exceptions:

- The maximum differential output voltage (V_{OD}) is increased to 600 mV. The maximum V_{OD} for ANSI specification is 450 mV.
- The input voltage range is reduced to the range of 1.0 V to 1.6 V, 0.5 V to 1.85 V, or 0 V to 1.8 V based on different frequency ranges. The ANSI/TIA/EIA-644 specification supports an input voltage range of 0 V to 2.4 V.
- For LVDS I/O standard electrical specifications in Cyclone IV devices, refer to the *Cyclone IV Device Datasheet* chapter.

ACTIVE_DISENGAGE

The ACTIVE_DISENGAGE instruction places the active configuration controller (AS and AP) into an idle state prior to JTAG programming. The two purposes of placing the active controller in an idle state are:

- To ensure that it is not trying to configure the device during JTAG programming
- To allow the controllers to properly recognize a successful JTAG programming that results in the device reaching user mode

The ACTIVE_DISENGAGE instruction is required before JTAG programming regardless of the current state of the Cyclone IV device if the MSEL pins are set to an AS or AP configuration scheme. If the ACTIVE_DISENGAGE instruction is issued during a passive configuration scheme (PS or FPP), it has no effect on the Cyclone IV device. Similarly, the CONFIG_IO instruction is issued after an ACTIVE_DISENGAGE instruction, but is no longer required to properly halt configuration. Table 8–17 lists the required, recommended, and optional instructions for each configuration mode. The ordering of the required instructions is a hard requirement and must be met to ensure functionality.

		Configuration Scheme and Current State of the Cyclone IV Device										
JTAG Instruction	Prior to User Mode (Interrupting Configuration)					User Mode			Power Up			
	PS	FPP	AS	AP	PS	FPP	AS	AP	PS	FPP	AS	AP
ACTIVE_DISENGAGE	0	0	R	R	0	0	0	R	0	0	R	R
CONFIG_IO	Rc	Rc	0	0	0	0	0	0	NA	NA	NA	NA
Other JTAG instructions	0	0	0	0	0	0	0	0	0	0	0	0
JTAG_PROGRAM	R	R	R	R	R	R	R	R	R	R	R	R
CHECK_STATUS	Rc	Rc	Rc	Rc	Rc	Rc	Rc	Rc	Rc	Rc	Rc	Rc
JTAG_STARTUP	R	R	R	R	R	R	R	R	R	R	R	R
JTAG TAP Reset/other instruction	R	R	R	R	R	R	R	R	R	R	R	R

Table 8–17. JTAG Programming Instruction Flows (1)

Note to Table 8-17:

(1) "R" indicates that the instruction must be executed before the next instruction, "O" indicates the optional instruction, "Rc" indicates the recommended instruction, and "NA" indicates that the instruction is not allowed in this mode.

In the AS or AP configuration scheme, the ACTIVE_DISENGAGE instruction puts the active configuration controller into idle state. If a successful JTAG programming is executed, the active controller is automatically re-engaged after user mode is reached through JTAG programming. This causes the active controller to transition to their respective user mode states.

If JTAG programming fails to get the Cyclone IV device to enter user mode and re-engage active programming, there are available methods to achieve this:

■ In AS configuration scheme, you can re-engage the AS controller by moving the JTAG TAP controller to the reset state or by issuing the ACTIVE_ENGAGE instruction.

Pin Name	User Mode	Configuration Scheme	Pin Type	Description
				In an AS or PS configuration scheme, DATA [72] function as user I/O pins during configuration, which means they are tri-stated.
	1/0	FPP ΔP <i>(2)</i>	Inputs (FPP). Bidirectional	After FPP configuration, DATA [72] are available as user I/O pins and the state of these pin depends on the Dual-Purpose Pin settings.
			(AP) (2)	In an AP configuration scheme, for Cyclone IV E devices only, the byte-wide or word-wide configuration data is presented to the target Cyclone IV E device on DATA[70] or DATA[150], respectively. After AP configuration, DATA[72] are dedicated bidirectional pins with optional user control. ⁽²⁾
				Data inputs. Word-wide configuration data is presented to the target Cyclone IV E device on DATA[150].
DATA [158]	I/O	AP (2)	Bidirectional	In a PS, FPP, or AS configuration scheme, DATA [15:8] function as user I/O pins during configuration, which means they are tri stated.
				After AP configuration, DATA [15:8] are dedicated bidirectional pins with optional user control.
PADD [230]	I/O	AP (2)	Output	In AP mode, it is a 24-bit address bus from the Cyclone IV E device to the parallel flash. Connects to the A [24:1] bus on the Micron P30 or P33 flash.
nRESET	I/O	AP (2)	Output	Active-low reset output. Driving the nRESET pin low resets the parallel flash. Connects to the RST# pin on the Micron P30 or P33 flash.
nAVD	I/O	AP (2)	Output	Active-low address valid output. Driving the nAVD pin low during read or write operation indicates to the parallel flash that a valid address is present on the PADD $[230]$ address bus. Connects to the ADV# pin on the Micron P30 or P33 flash.
nOE	I/O	AP (2)	Output	Active-low output enable to the parallel flash. During the read operation, driving the nOE pin low enables the parallel flash outputs (DATA [150]). Connects to the OE# pin on the Micron P30 or P33 flash.
nWE	I/O	AP (2)	Output	Active-low write enable to the parallel flash. During the write operation, driving the nWE pin low indicates to the parallel flash that data on the DATA [150] bus is valid. Connects to the WE# pin on the Micron P30 or P33 flash.

Table 8–20. Dec	dicated Configurat	tion Pins on the	Cyclone IV Device	(Part 4 of 4)
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Note to Table 8-20:

(1) If you are accessing the EPCS device with the ALTASMI_PARALLEL megafunction or your own user logic in user mode, in the **Device and Pin Options** window of the Quartus II software, in the **Dual-Purpose Pins** category, select **Use as regular I/O** for this pin.

(2) The AP configuration scheme is for Cyclone IV E devices only.

The user watchdog timer is disabled in factory configurations and during the configuration cycle of the application configuration. It is enabled after the application configuration enters user mode.

Quartus II Software Support

Implementation in your design requires a remote system upgrade interface between the Cyclone IV device logic array and remote system upgrade circuitry. You must also generate configuration files for production and remote programming of the system configuration memory. The Quartus II software provides these features.

The two implementation options, ALTREMOTE_UPDATE megafunction and remote system upgrade atom, are for the interface between the remote system upgrade circuitry and the device logic array interface. Using the megafunction block instead of creating your own logic saves design time and offers more efficient logic synthesis and device implementation.

• For more information about the ALTREMOTE_UPDATE megafunction, refer to the *Remote Update Circuitry (ALTREMOTE_UPDATE) Megafunction User Guide*.

Document Revision History

Table 8–28 lists the revision history for this chapter.

abie 0-20. Ducui								
Date	Version	Changes						
		■ Added Table 8–6.						
		 Updated Table 8–9 to add new device options and packages. 						
May 2013	1.7	■ Updated Figure 8–16 and Figure 8–22 to include user mode.						
		Updated the "Dedicated" column for DATA[0] and DCLK in Table 8–19.						
		 Updated the "User Mode" and "Pin Type" columns for DCLK in Table 8–20. 						
ebruary 2013	1.6	Updated Table 8–9 to add new device options and packages.						
		 Updated "AP Configuration Supported Flash Memories", "Configuration Data Decompression", and "Overriding the Internal Oscillator" sections. 						
October 2012	1.5	 Updated Figure 8–3, Figure 8–4, Figure 8–5, Figure 8–7, Figure 8–8, Figure 8–9, Figure 8–10, and Figure 8–11. 						
		■ Updated Table 8–2, Table 8–8, Table 8–12, Table 8–13, Table 8–18, and Table 8–						
		 Added information about how to gain control of EPCS pins. 						
		 Updated "Reset", "Single-Device AS Configuration", "Single-Device AP Configuration", and "Overriding the Internal Oscillator" sections. 						
November 2011	1.4	■ Added Table 8–7.						
		■ Updated Table 8–6 and Table 8–19.						
		■ Updated Figure 8–3, Figure 8–4, and Figure 8–5.						
		 Updated for the Quartus II software version 10.1 release. 						
December 2010	1.2	 Added Cyclone IV E new device package information. 						
	1.0	■ Updated Table 8–7, Table 8–10, and Table 8–11.						
		 Minor text edits. 						

Table 8–28. Document Revision History (Part 1 of 2)

8-19.

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Table 9–4 defines the registers shown in Figure 9–1.

 Table 9–4.
 Error Detection Registers

Register	Function
32-bit signature register	This register contains the CRC signature. The signature register contains the result of the user mode calculated CRC value compared against the pre-calculated CRC value. If no errors are detected, the signature register is all zeros. A non-zero signature register indicates an error in the configuration CRAM contents.
	The CRC_ERROR signal is derived from the contents of this register.
32-bit storage register	This register is loaded with the 32-bit pre-computed CRC signature at the end of the configuration stage. The signature is then loaded into the 32-bit CRC circuit (called the Compute and Compare CRC block, as shown in Figure 9–1) during user mode to calculate the CRC error. This register forms a 32-bit scan chain during execution of the CHANGE_EDREG JTAG instruction. The CHANGE_EDREG JTAG instruction can change the content of the storage register. Therefore, the functionality of the error detection CRC circuitry is checked in-system by executing the instruction to inject an error during the operation. The operation of the device is not halted when issuing the CHANGE_EDREG instruction.

Error Detection Timing

When the error detection CRC feature is enabled through the Quartus II software, the device automatically activates the CRC process upon entering user mode after configuration and initialization is complete.

The CRC_ERROR pin is driven low until the error detection circuitry detects a corrupted bit in the previous CRC calculation. After the pin goes high, it remains high during the next CRC calculation. This pin does not log the previous CRC calculation. If the new CRC calculation does not contain any corrupted bits, the CRC_ERROR pin is driven low. The error detection runs until the device is reset.

The error detection circuitry runs off an internal configuration oscillator with a divisor that sets the maximum frequency.

Table 9–5 lists the minimum and maximum error detection frequencies.

Table 9–5. Minimum and Maximum Error Detection Frequencies for Cyclone IV Devices

Error Detection	Maximum Error	Minimum Error	Valid Divisors (2ª)	
Frequency	Detection Frequency	Detection Frequency		
80 MHz/2 ⁿ	80 MHz	312.5 kHz	0, 1, 2, 3, 4, 5, 6, 7, 8	

You can set a lower clock frequency by specifying a division factor in the Quartus II software (for more information, refer to "Software Support"). The divisor is a power of two (2), where *n* is between 0 and 8. The divisor ranges from one through 256. Refer to Equation 9–1.

Equation 9-1.

ror detection frequency	=	80 MH
in accelering accelering		2^n

CRC calculation time depends on the device and the error detection clock frequency.

Bit-Slip Mode

In bit-slip mode, the rx_bitslip port controls the word aligner operation. At every rising edge of the rx_bitslip signal, the bit-slip circuitry slips one bit into the received data stream, effectively shifting the word boundary by one bit. When the received data after bit-slipping matches the programmed word alignment pattern, the rx_patterndetect signal is driven high for one parallel clock cycle.

You can implement a bit-slip controller in the user logic that monitors either the rx_patterndetect signal or the receiver data output (rx_dataout), and controls the rx bitslip port to achieve word alignment.

Figure 1–18 shows an example of the word aligner configured in bit-slip mode. For this example, consider that 8'b1110000 is received back-to-back and 16'b0000111100011110 is specified as the word alignment pattern. A rising edge on the rx_bitslip signal at time n + 1 slips a single bit 0 at the MSB position, forcing the rx_dataout to 8'b01111000. Another rising edge on the rx_bitslip signal at time n + 5 forces rx_dataout to 8'b00111100. Another rising edge on the rx_bitslip signal at time n + 9 forces rx_dataout to 8'b0011110. Another rising edge on the rx_bitslip signal at time n + 9 forces rx_dataout to 8'b00011110. Another rising edge on the rx_bitslip signal at time n + 13 forces the rx_dataout to 8'b0001111. At this instance, rx_dataout in cycles n + 12 and n + 13 is 8'b00011110 and 8'b00001111, respectively, which matches the specified 16-bit alignment pattern 16'b0000111100011110. This results in the assertion of the rx_patterndetect signal.





Automatic Synchronization State Machine Mode

In automatic synchronization state machine mode, the word aligner achieves synchronization after receiving a specific number of synchronization code groups, and falls out of synchronization after receiving a specific number of erroneous code groups. This mode provides hysteresis during link synchronization, which is required by protocols such as PCIe, GbE, XAUI, and Serial RapidIO.

This mode is only supported using the 8B/10B encoded data with 10-bit input to the word aligner.

Figure 1–36 and Figure 1–37 show the independent high-speed clock and bonded low-speed clock distributions for transceivers in F324 and smaller packages, and in F484 and larger packages in bonded (×2 and ×4) channel configuration.

Figure 1–36. Clock Distribution in Bonded (×2 and ×4) Channel Configuration for Transceivers in F324 and Smaller Packages.



Notes to Figure 1-36:

- (1) Transceiver channels 2 and 3 are not available for devices in F169 and smaller packages.
- (2) High-speed clock.
- (3) Low-speed clock.
- (4) Bonded common low-speed clock path.

The calibration block internally generates a constant internal reference voltage, independent of PVT variations and uses this voltage and the external reference resistor on the RREF pin to generate constant reference currents. The OCT calibration circuit calibrates the OCT resistors present in the transceiver channels. Figure 1–41 shows the calibration block diagram.





Notes to Figure 1-41:

- (1) All transceiver channels use the same calibration block clock and power down signals.
- (2) Connect a 2 k Ω (tolerance max ± 1%) external resistor to the RREF pin to ground. The RREF resistor connection in the board must be free from any external noise.
- (3) Supports up to 125 MHz clock frequency. Use either dedicated global clock or divide-down logic from the FPGA fabric to generate a slow clock on the local clock routing.
- (4) The calibration block restarts the calibration process following deassertion of the cal_blk_powerdown signal.

PCI-Express Hard IP Block

Figure 1–42 shows the block diagram of the PCIe hard IP block implementing the PHY MAC, Data Link Layer, and Transaction Layer for PCIe interfaces. The PIPE interface is used as the interface between the transceiver and the hard IP block.

Figure 1–42. PCI Express Hard IP High-Level Block Diagram



Figure 1–55 shows the transceiver channel datapath and clocking when configured in GIGE mode.





Notes to Figure 1-55:

- (1) Low-speed recovered clock.
- (2) High-speed recovered clock.

(3) Optional rx_recovclkout port from CDR low-speed recovered clock is available for applications such as Synchronous Ethernet.

Figure 1–60 shows the transceiver channel datapath and clocking when configured in Serial RapidIO mode.





Notes to Figure 1–60:

- (1) Optional rate match FIFO.
- (2) High-speed recovered clock.
- (3) Low-speed recovered clock.

Figure 1–72 shows the two paths in reverse serial loopback mode.

Figure 1–72. Reverse Serial Loopback ⁽¹⁾



Notes to Figure 1-72:

- (1) Grayed-Out Blocks are Not Active in this mode.
- (2) Post-CDR reverse serial loopback path.
- (3) Pre-CDR reverse serial loopback path.

Self Test Modes

Each transceiver channel in the Cyclone IV GX device contains modules for pattern generator and verifier. Using these built-in features, you can verify the functionality of the functional blocks in the transceiver channel without requiring user logic. The self test functionality is provided as an optional mechanism for debugging transceiver channels.

There are three types of supported pattern generators and verifiers:

- Built-in self test (BIST) incremental data generator and verifier—test the complete transmitter PCS and receiver PCS datapaths for bit errors with parallel loopback before the PMA blocks.
- Pseudo-random binary sequence (PRBS) generator and verifier—the PRBS generator and verifier interface with the serializer and deserializer in the PMA blocks. The advantage of using a PRBS data stream is that the randomness yields an environment that stresses the transmission medium. In the data stream, you can observe both random jitter and deterministic jitter using a time interval analyzer, bit error rate tester, or oscilloscope.
- High frequency and low frequency pattern generator—the high frequency patterns generate alternate ones and zeros and the low frequency patterns generate five ones and five zeroes. These patterns do not have a corresponding verifier.

The self-test features are only supported in Basic mode.

Block	Port Name	Input/ Output	Clock Domain	Description		
				Rate match FIFO full status indicator.		
			Synchronous to tx clkout	A high level indicates the rate match FIFO is full.		
	rx_rmfifofull (Output	(non-bonded modes) or coreclkout (bonded modes)	 Driven for a minimum of two serial clock cycles in configurations without a byte serializer and a minimum of three recovered clock cycles in configurations with a byte serializer. 		
			Synchronous to tx_clkout (non-bonded modes) or coreclkout (bonded modes)	Rate match FIFO empty status indicator.		
	rx_rmfifoempty			A high level indicates the rate match FIFO is empty.		
		Output		Driven for a minimum of two serial clock cycles in configurations without a byte serializer and a minimum of three recovered clock cycles in configurations with a byte serializer.		
			Synchronous to tx_clkout (non-bonded modes) or coreclkout (bonded modes)	8B/10B decoder control or data identifier.		
	rx_ctrldetect	Output		 A high level indicates received code group is a /Kx.y/ control code group. 		
				 A low level indicates received code group is a /Dx.y/ data code group. 		
	rx_errdetect		Synchronous to tx_clkout (non-bonded modes) or coreclkout (bonded modes)	8B/10B code group violation or disparity error indicator.		
				 A high level indicates that a code group violation or disparity error was detected on the associated received code group. 		
		Output		 Use with the rx_disperr signal to differentiate between a code group violation or a disparity error as follows: [rx_errdetect:rx_disperr] 		
RX PCS				 2'b00—no error 		
				 2'b10—code group violation 		
				 2'b11—disparity error or both 		
		Output	Synchronous to tx_clkout (non-bonded modes) or coreclkout (bonded modes)	8B/10B disparity error indicator.		
	rx_disperr			 A high level indicates that a disparity error was detected on the associated received code group. 		
		Output	Synchronous to tx_clkout (non-bonded modes) or coreclkout (bonded modes)	8B/10B current running disparity indicator.		
	rx_runningdisp			 A high level indicates a positive current running disparity at the end of the decoded byte 		
				 A low level indicates a negative current running disparity at the end of the decoded byte 		
	rx_enabyteord			Enable byte ordering control		
		Input	Asynchronous signal	 A low-to-high transition triggers the byte ordering block to restart byte ordering operation. 		
	rx_byteorder alignstatus			Byte ordering status indicator.		
		Output	Synchronous to tx_clkout (non-bonded modes) or coreclkout (bonded modes)	A high level indicates that the byte ordering block has detected the programmed byte ordering pattern in the least significant byte of the received data from the byte deserializer.		
			Synchronous to tx_clkout	Parallel data output from the receiver to the FPGA fabric.		
	rx_dataout Output		(non-bonded modes) or coreclkout (bonded modes)	 Bus width depends on channel width multiplied by number of channels per instance. 		

Table 1–27. Receiver Ports in ALTGX Megafunction for Cyclone IV GX (Part 2 of 3)

Table 3–7 lists the ALTGX megafunction ports for PLL Reconfiguration mode.

Port Name ⁽¹⁾	Input/ Output	Description	Comments
pll_areset [n0]	Input	 Resets the transceiver PLL. The pll_areset are asserted in two conditions: Used to reset the transceiver PLL during the reset sequence. During reset sequence, this signal is user controlled. After the transceiver PLL is reconfigured, this signal is asserted high by the ALTPLL_RECONFIG controller. At this time, this signal is not user controlled. 	You must connect the pll_areset port of ALTGX to the pll_areset port of the ALTPLL_RECONFIG megafunction. The ALTPLL_RECONFIG controller asserts the pll_areset port at the next rising clock edge after the pll_reconfig_done signal from the ALTGX megafunction goes high. After the pll_reconfig_done signal goes high, the transceiver PLL is reset. When the PLL reconfiguration is completed, this reset is performed automatically by the ALTPLL_RECONFIG megafunction and is not user controlled.
pll_scandata [n0]	Input	Receives the scan data input from the ALTPLL_RECONFIG megafunction.	The reconfigurable transceiver PLL received the scan data input through this port for the dynamically reconfigurable bits from the ALTPLL_RECONFIG controller.
pll_scanclk [n0]	Input	Drives the scanclk port on the reconfigurable transceiver PLL.	Connect the pll_scanclk port of the ALTGX megafunction to the ALTPLL_RECONFIG scanclk port.
pll_scancikena [n0]	Input	Acts as a clock enable for the scanclk port on the reconfigurable transceiver PLL.	Connect the pll_scanclkena port of the ALTGX megafunction to the ALTPLL_RECONFIG scanclk port.
pll_configupdate [n0]	Input	Drives the configupdate port on the reconfigurable transceiver PLL.	This port is connected to the pll_configupdate port from the ALTPLL_RECONFIG controller. After the final data bit is sent out, the ALTPLL_RECONFIG controller asserts this signal.
pll_reconfig_done[n0]	Output	This signal is asserted to indicate the reconfiguration process is done.	Connect the pll_reconfig_done port to the pll_scandone port on the ALTPLL_RECONFIG controller. The transceiver PLL scandone output signal drives this port and determines when the PLL is reconfigured.
pll_scandataout [n0]	Output	This port scan out the current configuration of the transceiver PLL.	Connect the pll_scandataout port to the pll_scandataout port of the ALTPLL_RECONFIG controller. This port reads the current configuration of the transceiver PLL and send it to the ALTPLL_RECONFIG megafunction.

Table 3–7. ALTGX Megafunction Port List for PLL Reconfiguration Mode

Note to Table 3-7:

(1) $\langle n \rangle$ = (number of transceiver PLLs configured in the ALTGX MegaWizard) - 1.

• For more information about the ALTPLL_RECONFIG megafunction port list, description and usage, refer to the *Phase-Locked Loop Reconfiguration* (*ALTPL_RECONFIG*) *Megafunction User Guide*.

If you are reconfiguring the multipurpose PLL with a different M counter value, follow these steps:

- 1. During transceiver PLL reconfiguration, assert tx_digitalreset, rx_digitalreset, and rx_analogreset signals.
- 2. Perform PLL reconfiguration to update the multipurpose PLL with the PLL **.mif** files.
- 3. Perform channel reconfiguration and update the transceiver with the GXB reconfiguration **.mif** files. If you have multiple channel instantiations connected to the same multipurpose PLL, reconfigure each channel.
- 4. Deassert tx_digitalreset and rx_analogreset signals.
- 5. After the rx_freqlocked signal goes high, wait for at least 4 µs, and then deassert the rx_digitalreset signal.

Error Indication During Dynamic Reconfiguration

The ALTGX_RECONFIG MegaWizard Plug-In Manager provides an error status signal when you select the **Enable illegal mode checking** option or the **Enable self recovery** option in the **Error checks/data rate switch** screen. The conditions under which the error signal is asserted are:

- Enable illegal mode checking option—when you select this option, the dynamic reconfiguration controller checks whether an attempted operation falls under one of the conditions listed below. The dynamic reconfiguration controller detects these conditions within two reconfig_clk cycles, deasserts the busy signal, and asserts the error signal for two reconfig_clk cycles.
 - PMA controls, read operation—none of the output ports (rx_eqctrl_out, rx_eqdcgain_out, tx_vodctrl_out, and tx_preemp_out) are selected in the ALTGX_RECONFIG instance and the read signal is asserted.
 - PMA controls, write operation—none of the input ports (rx_eqctrl, rx_eqdcgain, tx_vodctrl, and tx_preemp) are selected in the ALTGX_RECONFIG instance and the write_all signal is asserted.
- Channel reconfiguration and PMA reconfiguration mode select read operation option:
 - The reconfig_mode_sel input port is set to 3'b001 (Channel reconfiguration mode)
 - The read signal is asserted
- Enable self recovery option—when you select this option, the ALTGX_RECONFIG MegaWizard Plug-In Manager provides the error output port. The dynamic reconfiguration controller quits an operation if it did not complete within the expected number of clock cycles. After recovering from the illegal operation, the dynamic reconfiguration controller deasserts the busy signal and asserts the error output port for two reconfig_clk cycles.
- The error signal is not asserted when an illegal value is written to any of the PMA controls.

Example 1–1 shows how to calculate the change of 50- Ω I/O impedance from 25°C at 3.0 V to 85°C at 3.15 V.

Example 1–1. Impedance Change

$$\begin{split} \Delta R_V &= (3.15-3) \times 1000 \times -0.026 = -3.83 \\ \Delta R_T &= (85-25) \times 0.262 = 15.72 \\ \text{Because } \Delta R_V \text{ is negative,} \\ MF_V &= 1 \ / \ (3.83/100 + 1) = 0.963 \\ \text{Because } \Delta R_T \text{ is positive,} \\ MF_T &= 15.72/100 + 1 = 1.157 \\ MF &= 0.963 \times 1.157 = 1.114 \\ R_{\text{final}} &= 50 \times 1.114 = 55.71 \ \Omega \end{split}$$

Pin Capacitance

Table 1–11 lists the pin capacitance for Cyclone IV devices.

Table 1–11.	Pin Cap	acitance for	Cvclone I	V Devices	(1)
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Symbol	Parameter	Typical – Quad Flat Pack (QFP)	Typical – Quad Flat No Leads (QFN)	Typical – Ball-Grid Array (BGA)	Unit
CIOTB	Input capacitance on top and bottom I/O pins	7	7	6	pF
C _{IOLR}	Input capacitance on right I/O pins	7	7	5	pF
C _{LVDSLR}	Input capacitance on right I/O pins with dedicated LVDS output	8	8	7	pF
C _{VREFLR}	Input capacitance on right dual-purpose ${\tt VREF}$ pin when used as $V_{\sf REF}$ or user I/O pin	21	21	21	pF
C _{VREFTB}	Input capacitance on top and bottom dual-purpose \mathtt{VREF} pin when used as $V_{\textrm{REF}}$ or user I/O pin	23 <i>(3)</i>	23	23	pF
C _{CLKTB}	Input capacitance on top and bottom dedicated clock input pins	7	7	6	pF
C _{CLKLR}	Input capacitance on right dedicated clock input pins	6	6	5	pF

Notes to Table 1-11:

(1) The pin capacitance applies to FBGA, UBGA, and MBGA packages.

(2) When you use the vref pin as a regular input or output, you can expect a reduced performance of toggle rate and t_{CO} because of higher pin capacitance.

(3) C_{VREFTB} for the EP4CE22 device is 30 pF.